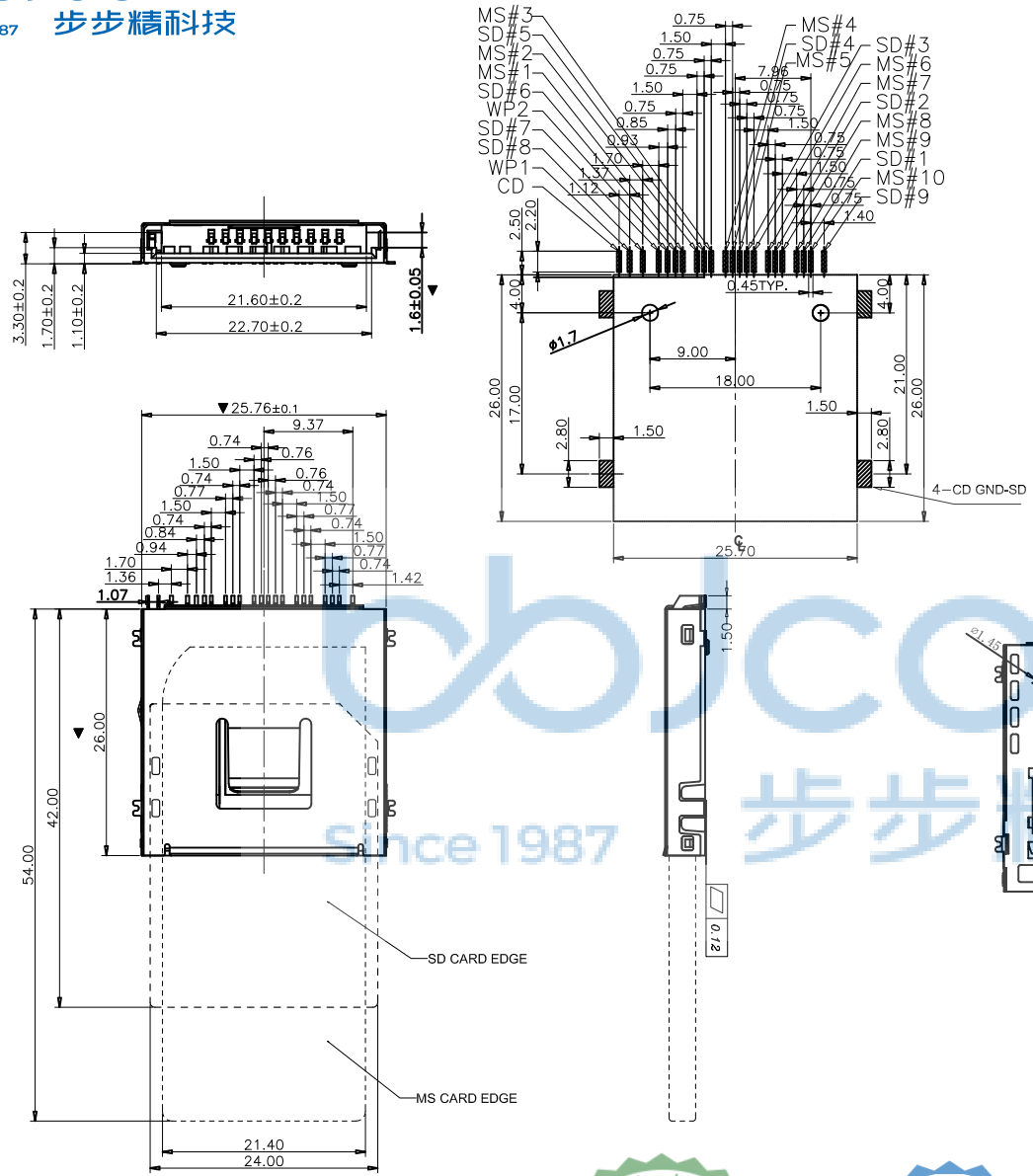


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

NOTES:
 MATERIALS:
 HOUSING : ENGINEERING THERMOPLASTIC
 UL 94V-0. BLACK
 CONTACT : COPPER ALLOY
 COVER : COPPER ALLOY
 FINISH:
 CONTACT AREA: GOLD OVER NICKEL.
 SOLDER AREA : TIN OVER NICKEL.
 PERFORMANCE CHARACTERISTICS:
 CURRENT RATING : 0.5 A AC DC
 VOLTAGE RATING : 500VAC MIN.
 CONTACT RESISTANCE : 100 MILLIOHMS MAX.
 INSULATION RESISTANCE : 1000 MEGOHMS MIN . AT 500VDC.
 OPERATING TEMPERATUER : -25° C TO 85° C.



PCB LAYOUT

MS CARD PIN DESIGN		SD CARD PIN DESIGN		
Pin#	Name	Pin#	Name	Description
1#	VSS	1#	CD/DAT3	Card Detect/DATA 1/0
2#	BS	2#	CMD	COMMAND
3#	VCC	3#	Vss1	GROUND
4#	DIO	4#	V _{DD}	POWER
5#	RESERVE	5#	CLK	Clock
6#	INS	6#	Vss2	GROUND
7#	RESERVE	7#	DAT0	Data 1/0
8#	SCLK	8#	DAT1	Data 1/0
9#	VCC	9#	DAT2	Data 1/0
10#	VSS	9#	DAT2	Data 1/0



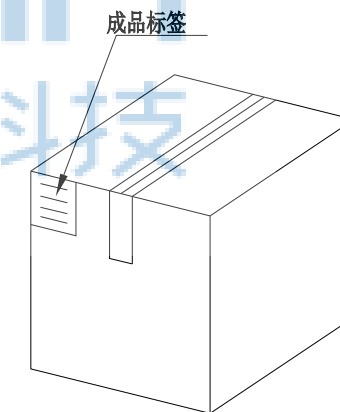
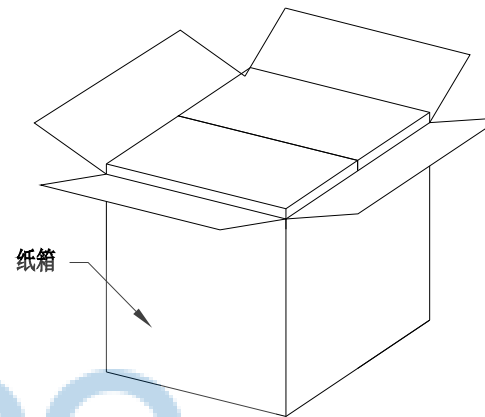
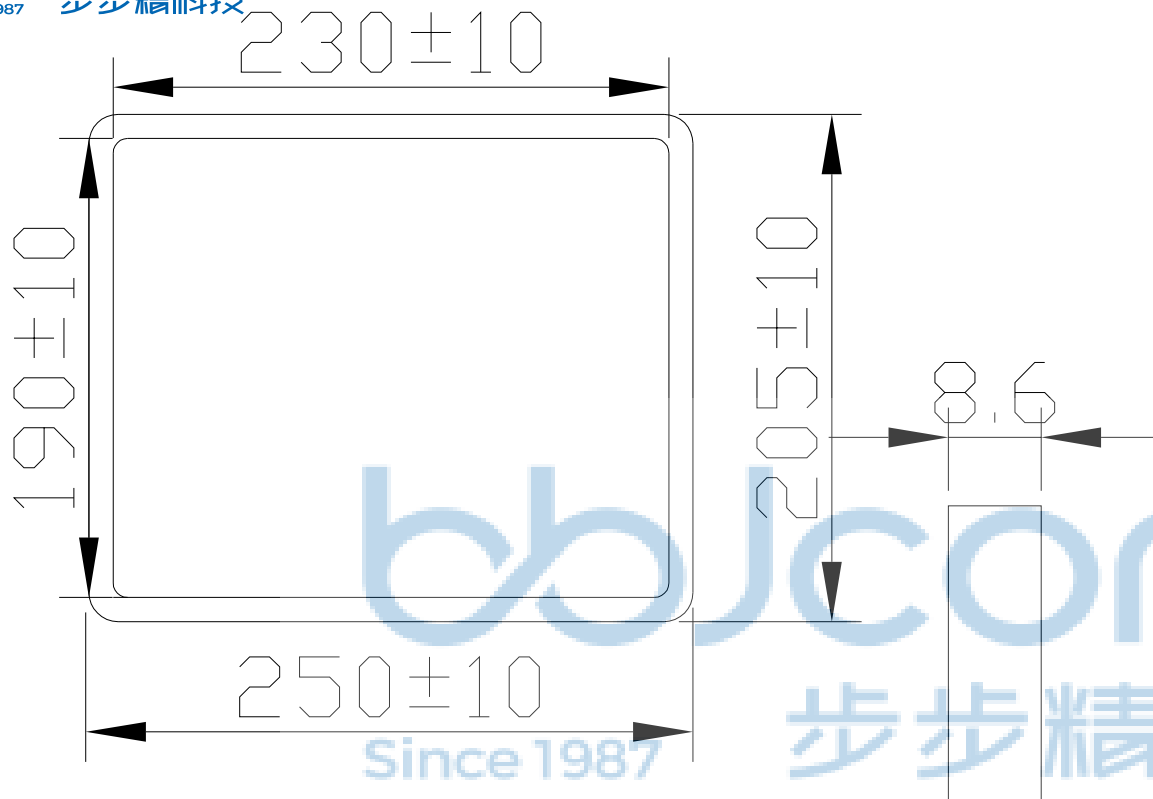
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 PDWNG.NO: 0214-1

深圳市步步精科技有限公司

NAME: 卡座 SIM 三合一 贴片 带柱 H=4.30

APPD. JM_Zheng
 CHKD. LYX
 DR. SGF

PJ. NO.: CD.04.01-02-0001
 SIZE: A4 DRW NO.:
 FINISH: SEE NOTES MAT'L.: SEE NOTES
 SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2



1. 包装要求:

- 1.1 每盒吸塑盒包装40pcs;
- 1.2 每25盘放一箱, 共计1000PCS;
- 1.3 纸箱外贴上标签



纸箱规格: 350*210*290

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APPD.	JM_Zheng	PJ. NO.: CD.04.01-02-0001 SIZE: A4 DRW NO.:		FINISH: SEE NOTES MAT'L.: SEE NOTES	
CHKD.	LYX	SCALE: N/A		REV.: A0	UNIT: mm
PDWG.NO:	0214-1	DR.	SGF	PAGE: 2/2	